

Pin Out

Thyristors

Surface Mount - 50V - 400V > MCR218-2G, MCR218-4G, MCR218-6G

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Description

Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supplies; or wherever half-wave silicon gate-controlled, solid-state devices are needed.

Features

Volts

Glass-Passivated
Junctions

• Blocking Voltage to 400

 TO-220 Construction – Low Thermal Resistance, High Heat Dissipation and Durability

Po

Functional Diagram



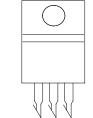
Additional Information



Resources









Maximum Ratings ($T_1 = 25^{\circ}C$ unless otherwise noted)

Rating		Symbol	Value	Unit
Peak Repetitive Off–State Voltage (Note 1) (– 40 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open)	MCR68-2	V _{drm} , V _{rrm}	50	V
On-State RMS Current (180° Conduction Angles; T _c = 85°C)		I _{TM (RMS)}	12	А
Peak Discharge Current (Note 2)		I _{TM}	300	А
Average On-State Current (180° Conduction Angles; T _c = 85°C)		I _{T(AV)}	8.0	А
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, T _J = 125°C)		I _{TSM}	100	А
Circuit Fusing Consideration (t = 8.3 ms)		l²t	40	A ² sec
Forward Peak Gate Current (Pulse Width \leq 1.0 $\mu sec, T_c =$ 80°C)		I _{GM}	2.0	A
Forward Peak Gate Current (Pulse Width \leq 1.0 $\mu sec, T_c =$ 85°C)		I _{GM}	20	W
Forward Average Gate Power (t = $8.3 \text{ ms}, \text{TC} = 85^{\circ}\text{C}$)		P _{G(AV)}	0.5	W
Operating Junction Temperature Range		TJ	-40 to +125	°C
Storage Temperature Range		T _{stg}	-40 to +150	°C
MountingTorque		_	8.0	in. lb.

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

2. Ratings apply for tw = 1 ms. See Figure 1 for I_{TM} capability for various duration of an exponentially decaying current waveform, tw is defined as 5 time constants of an exponentially decaying current pulse.

Thermal Characteristics

Rating		Symbol	Value	Unit
Thermal Resistance,	Junction-to-Case (AC) Junction-to-Ambient	R _{ejc} R _{eja}	2.0 60	°C/W
Maximum Lead Temperature for Soldering Purposes 10 seconds	TL	260	°C	

Electrical Characteristics - **OFF** (T = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Тур	Мах	Unit
Peak Repetitive Forward or Reverse Blocking Current	T_ = 25°C	I _{DRM} ,	-	-	10	
(VD = Rated VDRM and VRRM; Gate Open)	T_ = 125°C	I	-	-	2.0	mA

Electrical Characteristics \cdot **ON** (T₁ = 25°C unless otherwise noted)

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Characteristic	Symbol	Min	Тур	Max	Unit
Peak Forward On–State Voltage (Note 2) $(I_{TM} = 32 \text{ A})(I_{TM} = 24 \text{ A})$ (Note 3)	V _{TM}	-		2.2	V
$(I_{TM} = 300 \text{ A, tw} = 1 \text{ ms}) \text{ (Note 4)}$	1101	-	6.0	-	
Gate Trigger Current (Continuous dc) (V $_{\rm D}$ = 12 V; R $_{\rm L}$ = 100 $\Omega)$		2.0	7.0	30	mA
Gate Trigger Voltage (Continuous dc) (V $_{\rm D}$ = 12 V; R $_{\rm L}$ = 100 Ω)		_	0.65	1.5	V
Gate Trigger Non-Current (Continuous dc) ($V_{\rm D}$ = 12 V; $R_{\rm L}$ = 100 Ω)		0.2	0.40	_	V
Holding Current (V _p = 12 V, Initiating Current = 200 mA, Gate Open))		3.0	15	50	mA
Latch Current ($V_D = 12 \text{ V}, \text{ I}_G = 30 \text{ mA}$)		_	35	80	mA
Gate Controlled Turn-On Time (Note 5) ($V_p = Rated V_{DRMr} I_g = 150 \text{ mA}$) ($I_{TM} = 24 \text{ A Peak}$)		_	1.0	_	μs

Dynamic Characteristics						
Characteristic	Symbol	Min	Тур	Мах	Unit	
Critical Rate of Rise of Off–State Voltage ($V_D = Rated V_{DRM}$, Exponential Waveform, Gate Open, $T_J = 125^{\circ}C$)	dv/dt	10	-	-	V/µs	
Critical Rate of Rise of On–State Current $I_g = 150 \text{ A}$ $T_J = 125^{\circ}\text{C}$	di/dt	-	-	75	A/µs	

3. Pulse duration \leq 300 $\mu s,~duty~cycle \leq 2\,\%.$

4. Ratings apply for tw = 1 ms. See Figure 1 for I_{TM} capability for various durations of an exponentially decaying current waveform. tw is defined as 5 time constants of an exponentially decaying current pulse.

5. The gate controlled turn-on time in a crowbar circuit will be influenced by the circuit inductance.

Voltage Current Characteristic of SCR

Symbol	Parameter			
V _{DRM}	Peak Repetitive Forward Off State Voltage			
I _{DRM}	Peak Forward Blocking Current			
V _{RRM}	Peak Repetitive Reverse Off State Voltage			
I _{RRM}	Peak Reverse Blocking Current			
V _{TM}	Maximum On State Voltage			
I _H	Holding Current			

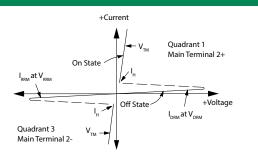




Figure 1. Current Derating

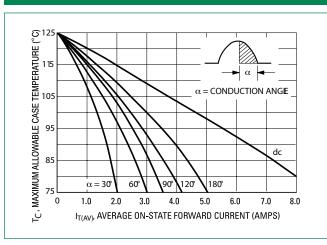


Figure 3. Typical Gate Trigger Current vsTemperature

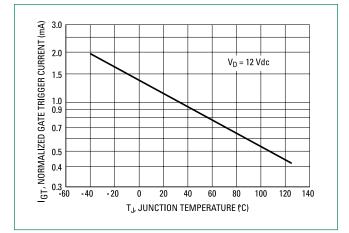


Figure 5. Typical Holding Current vs Temperature

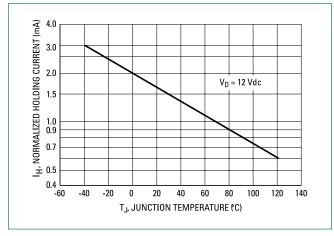


Figure 2. On-State Power Dissipation

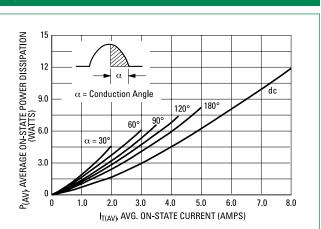
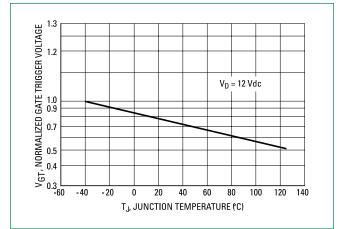


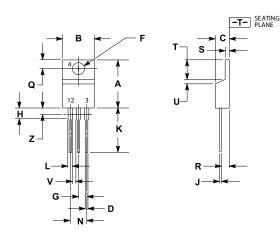
Figure 4. Typical Gate Trigger Voltage vs Temperature



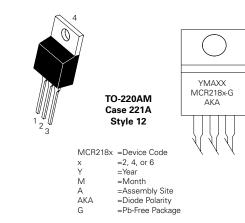


Dimensions

Expertise Applied Answers Delivered



Part Marking System



-	Inc	Inches		neters	
Dim	Min	Мах	Min	Max	
А	0.590	0.620	14.99	15.75	
В	0.380	0.420	9.65	10.67	
С	0.178	0.188	4.52	4.78	
D	0.025	0.035	0.64	0.89	
F	0.142	0.147	3.61	3.73	
G	0.095	0.105	2.41	2.67	
Н	0.110	0.130	2.79	3.30	
J	0.018	0.024	0.46	0.61	
К	0.540	0.575	13.72	14.61	
L	0.060	0.075	1.52	1.91	
Ν	0.195	0.205	4.95	5.21	
Q	0.105	0.115	2.67	2.92	
R	0.085	0.095	2.16	2.41	
S	0.045	0.060	1.14	1.52	
Т	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
V	0.045		1.15		
Z		0.080		2.04	

Cathode
Cathode
Anode
Gate
Anode

Ordering Information				
Device	Package	Shipping		
MCR218-2G				
MCR218-4G	TO-220AB (Pb-Free)	500 Units / Box		
MCR218-6G	(

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

2. CONTROLLING DIMENSION: INCH.

3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

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